

DFN1006-2L Plastic-Encapsulate ESD Protection Diodes

Features

- Low leakage current
- DFN1006 surface mount package
- IEC 61000-4-2 (ESD Air): $\pm 15\text{kV}$
- IEC 61000-4-2 (ESD Contact): $\pm 8\text{kV}$
- IEC 61000-4-5 (Lightning 8/20 μs): 2.5A

Applications

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Notebooks and Handhelds
- Portable Instrumentation, Digital Cameras
- Peripherals, Audio Players, Industrial Equipment

Function Diagram



Reverse Working Voltage
18V Max.
Ultra Small capacitance
0.6pF(Max.)

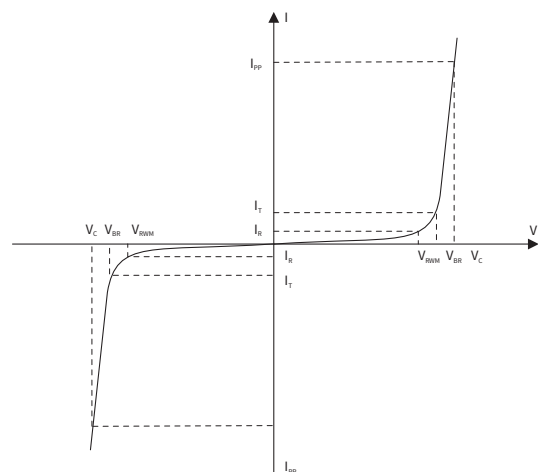


Maximum Ratings (Ta=25°C Unless otherwise specified)

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
V _{ESD}	Electrostatic Discharge Voltage	ESD per IEC 61000-4-2(Air)	± 15	KV
		ESD per IEC 61000-4-2(Contact)	± 8.0	KV
P _{PP}	Peak Pulse Power	tp = 8/20 μs	80	W
I _{PP}	Rated Peak Pulse Current	tp = 8/20 μs	2.5	A
T _J	Operating JunctionTemperature Range	—	-55 to +125	°C
T _{STG}	Operating JunctionTemperature Range	—	-55 to +150	°C

Electrical Parameter

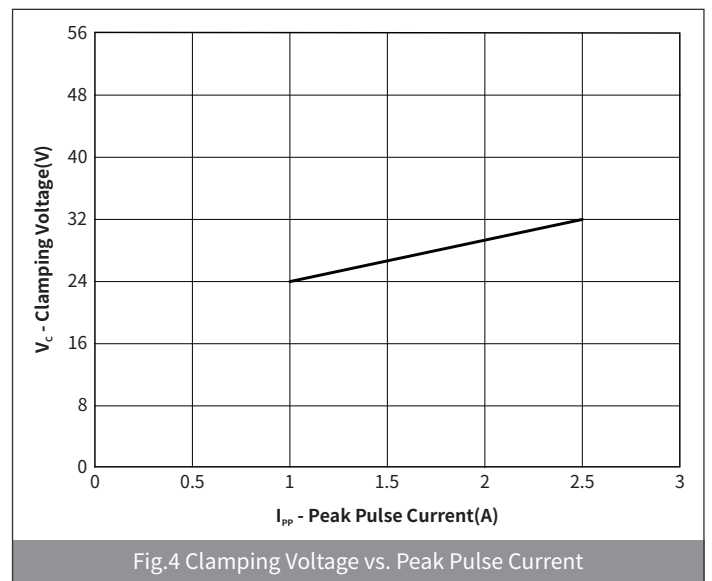
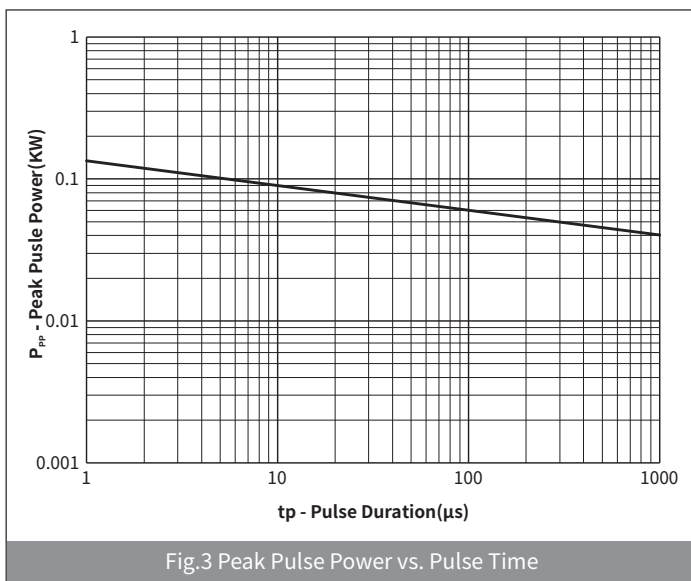
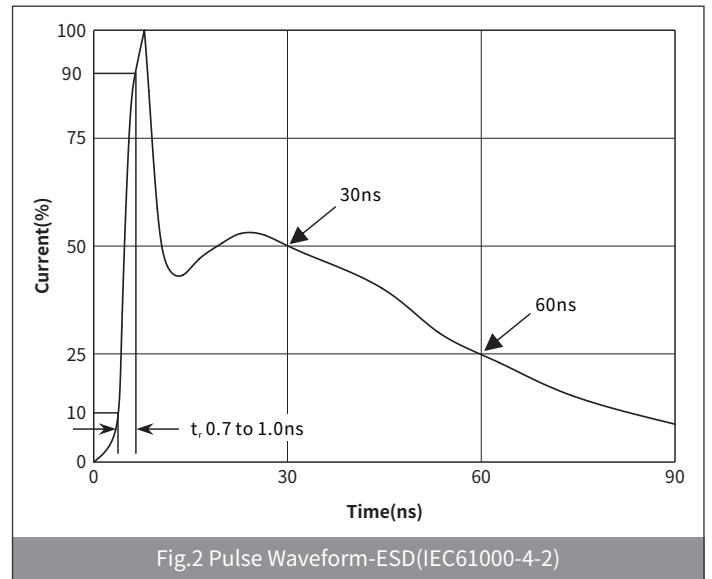
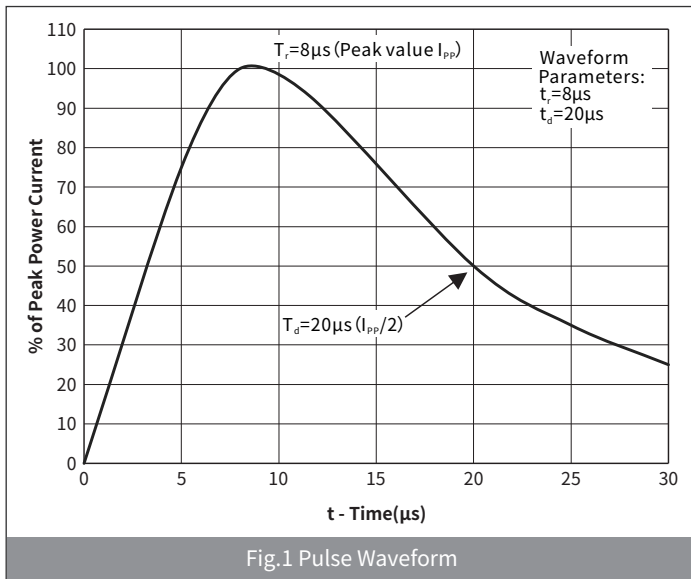
SYMBOL	PARAMETER
V _C	Clamping Voltage @ I _{PP}
V _{BR}	Breakdown Voltage @ I _T
I _{PP}	Peak Pulse Current
I _T	Test Current
I _R	Reverse Leakage Current @ VRWM
V _{RWM}	Peak Reverse Working Voltage
P _{PP}	Peak Pulse Power Dissipation
C _J	Junction Capacitance @ V _R =0V,f=1MHz
I _F	Forward Current
V _F	Forward Voltage @I _F



● **Electrical Characteristics** (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	CONDITION	Min	Typ	Max	UNIT
Peak Reverse Working Voltage	V_{RWM}	$T_a=25^{\circ}C$	—	—	18	V
Breakdown Voltage	V_{BR}	$I_T=10mA$	20.5	—	—	V
Reverse Leakage Current	I_R	$V_R=18V, T_a=25^{\circ}C$	—	—	0.2	μA
Clamping Voltage	V_C	$I_{PP}=1.0A, t_p=8/20\mu s$	—	—	26	V
		$I_{PP}=2.5A, t_p=8/20\mu s$	—	—	33	
Junction Capacitance	C_J	$V_R=0V, f=1MHz$	—	0.3	0.6	pF

● **Ratings And Characteristics Curves** (Ta=25°C Unless otherwise specified)



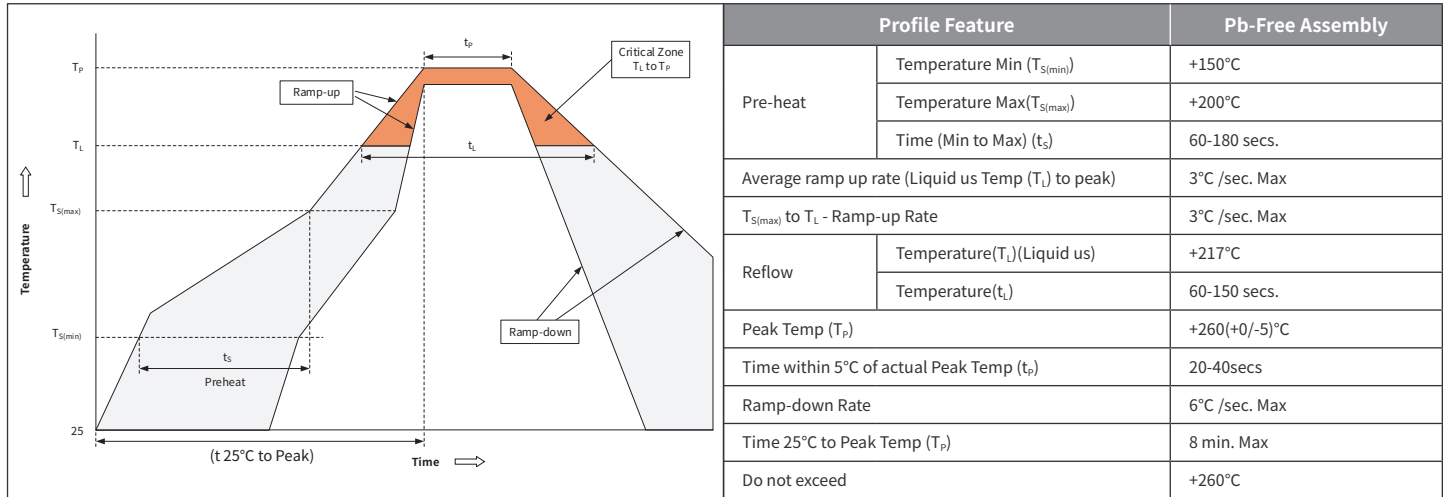
H18VU10B

Bi-directional 18V Ultra Small Capacitance ESD

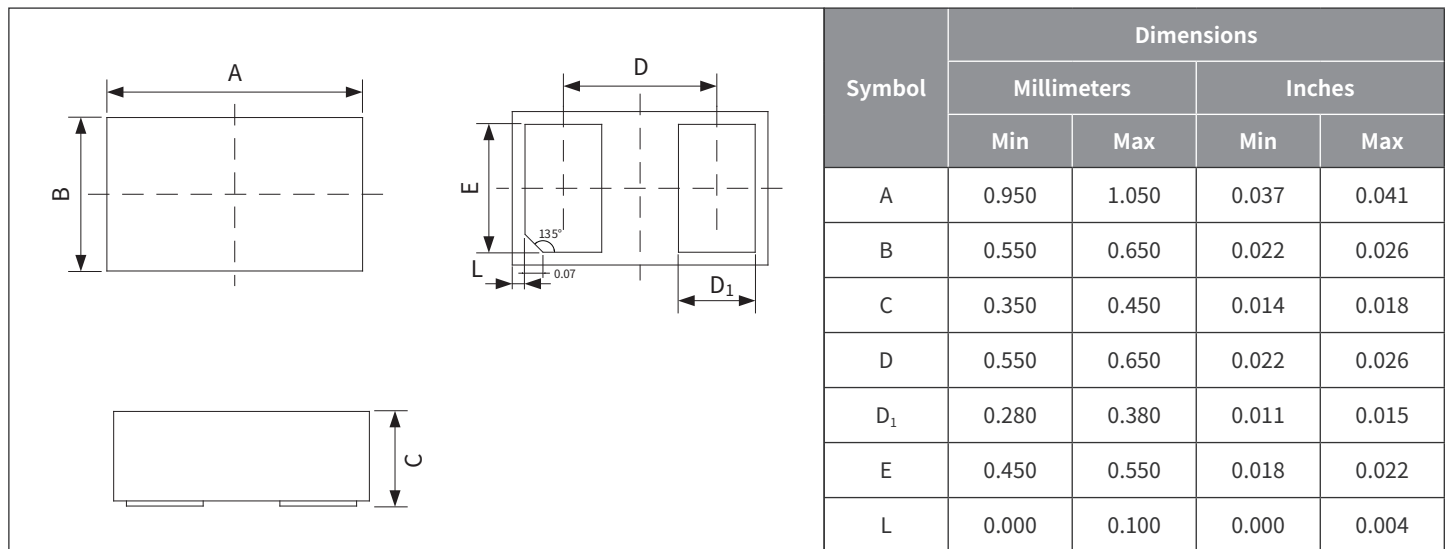
Ordering Information

PREFERRED P/N	PACKAGE	SIZE(mm)	DELIVERY MODE	MPQ(PCS)
H18VU10B	DFN1006-2L	1.00×0.60×0.37	7"	3000

Recommended Soldering Conditions



Package Outline Dimensions (DFN1006-2L)



Suggested Pad Layout

